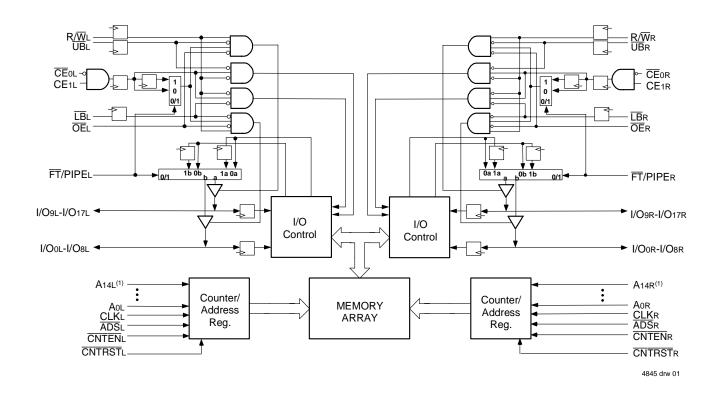
SYNCHR	EED 32/16K x 18709379ONOUS PIPELINED*709369ORT STATIC RAMRECOMMENDED FOR NEW DESIGNS
Features	
 True Dual-Ported memory cells which allow simultaneous access of the same memory location High-speed clock to data access Commercial: 7.5/9/12ns (max.) Insustrial: 9ns (max.) Low-power operation IDT709379/69L Active: 1.2W (typ.) Standby: 2.5mW (typ.) 	 Full synchronous operation on both ports 4ns setup to clock and 0ns hold on all control, data, and address inputs Data input, address, and control registers Fast 7.5ns clock to data out in the Pipelined output mode Self-timed write allows fast cycle time 10ns cycle time, 100MHz operation in Pipelined output mode Separate upper-byte and lower-byte controls for multiplexed bus and bus matching compatibility
 Flow-Through or Pipelined output mode on either Port via 	 TTL- compatible, single 5V (±10%) power supply
the FT/PIPE pins	 Industrial temperature range (-40°C to +85°C) is
Counter enable and reset features Deal action and the advector features	available for selected speeds
 Dual chip enables allow for depth expansion without additional logic 	 Available in a 100-pin Thin Quad Flatpack (TQFP) package Green parts available, see ordering information

Note that information regarding recently obsoleted parts is included in this datasheet for customer convenience.



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1. A14x is a NC for IDT709369.

NOTE:

FEBRUARY 2018

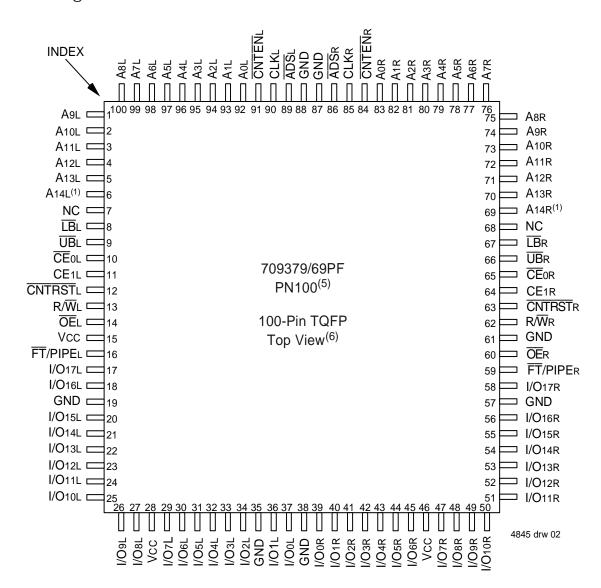
Functional Block Diagram

709379/69L

High-Speed 32/16K x 18 Synchronous Pipelined Dual-Port Static RAM

Description

The IDT709379/69 is a high-speed 32/16K x 18 bit synchronous Dual-Port RAM. The memory array utilizes Dual-Port memory cells to allow simultaneous access of any address from both ports. Registers on control, data, and address inputs provide minimal setup and hold times. The timing latitude provided by this approach allows systems to be designed with very short cycle times. With an input data register, the IDT709379/69 has been optimized for applications having unidirectional or bidirectional data flow in bursts. An automatic power down feature, controlled by $\overline{CE}0$ and CE1, permits the on-chip circuitry of each port to enter a very low standby power mode. Fabricated using CMOS high-performance technology, these devices typically operate on only 1.2W of power.



Pin Configurations^(1,2,3)

- 1. A14x is a NC for IDT709369.
- 2. All Vcc pins must be connected to power supply
- 3. All GND pins must be connected to ground.
- 4. Package body is approximately 14mm x 14mm x 1.4mm
- 5. This package code is used to reference the package diagram.
- 6. This text does not indicate orientation of the actual part-marking.

709379/69L High-Speed 32/16K x 18 Synchronous Pipelined Dual-Port Static RAM

Industrial and Commercial Temperature Ranges

Pin Names

Left Port	Right Port	Names
CE0L, CE1L	CEOR, CE1R	Chip Enables ⁽³⁾
R/WL	R/WR	Read/Write Enable
OEL	ŌĒR	Output Enable
Aol - A14L ⁽¹⁾	A0r - A14r ⁽¹⁾	Address
1/Ool - 1/017l	I/O0r - I/O17r	Data Input/Output
CLKL	CLKr	Clock
UBL	UB R	Upper Byte Select ⁽²⁾
LBL	LB R	Lower Byte Selectt ⁽²⁾
ADSL		Address Strobe
		Counter Enable
CNTRST L		Counter Reset
FT/PIPEL	FT /PIPER	Flow-Through/Pipeline
	Vcc	Power
(GND	Ground

NOTES:

1. A14x is a NC for IDT709369.

2. \overrightarrow{LB} and \overrightarrow{UB} are single buffered regardless of state of \overrightarrow{FT} /PIPE. 3. \overrightarrow{CE} o and CE1 are single buffered when \overrightarrow{FT} /PIPE = V_{IL}, \overline{CE} o and CE1 are double buffered when \overline{FT} /PIPE = VIH, i.e. the signals take two cycles to deselect.

4845 tbl 01

Truth Table I—Read/Write and Enable Control^(1,2,3)

ŌĒ	CLK	Ē	CE1	ŪB	ĪΒ	R/W	Upper Byte I/O9-17	Lower Byte I/O0-8	Mode
Х	\uparrow	Н	Х	Х	Х	Х	High-Z	High-Z	Deselected—Power Down
Х	\uparrow	Х	L	Х	Х	Х	High-Z	High-Z	Deselected—Power Down
Х	Ŷ	L	Н	Н	Н	Х	High-Z	High-Z	Both Bytes Deselected
Х	Ŷ	L	Н	L	Н	L	DATAIN	High-Z	Write to Upper Byte Only
Х	Ŷ	L	Н	Н	L	L	High-Z	DATAIN	Write to Lower Byte Only
Х	Ŷ	L	Н	L	L	L	DATAIN	DATAIN	Write to Both Bytes
L	Ŷ	L	Н	Г	Н	Н	DATAOUT	High-Z	Read Upper Byte Only
L	Ŷ	L	Н	Н	L	Н	High-Z	DATAOUT	Read Lower Byte Only
L	Ŷ	L	Н	L	L	Н	DATAOUT	DATAOUT	Read Both Bytes
Н	Х	L	Н	L	L	Х	High-Z	High-Z	Outputs Disabled

NOTES:

1. "H" = VIH, "L" = VIL, "X" = Don't Care. 2. \overline{ADS} , \overline{CNTEN} , \overline{CNTRST} = X.

3. OE is an asynchronous input signal.

4845 tbl 02

709379/69L High-Speed 32/16K x 18 Synchronous Pipelined Dual-Port Static RAM

Industrial and Commercial Temperature Ranges

4845 tbl 03

4845 tbl 05

Truth Table II—Address Counter Control^(1,2,6)

External Address	Previous Internal Address	Internal Address Used	CLK	ADS	CNTEN	CNTRST	I/O ⁽³⁾	MODE
An	Х	An	\uparrow	L ⁽⁴⁾	Х	Н	Dvo (n)	External Address Used
Х	An	An + 1	\uparrow	Н	L ⁽⁵⁾	Н	D⊮o(n+1)	Counter Enabled—Internal Address generation
Х	An + 1	An + 1	\uparrow	Н	Н	Н	D⊮o(n+1)	External Address Blocked—Counter disabled (An + 1 reused)
Х	Х	A0	\uparrow	Х	Х	L ⁽⁴⁾	Dvo(0)	Counter Reset to Address 0

NOTES:

1. "H" = VIH, "L" = VIL, "X" = Don't Care.

2. \overline{CE}_{0} , \overline{LB} , \overline{UB} , and \overline{OE} = VIL; CE1 and R/W = VIH.

3. Outputs configured in Flow-Through Output mode: if outputs are in Pipelined mode the data out will be delayed by one cycle.

4. \overline{ADS} is independent of all other signals including \overline{CE}_0 , CE_1 , \overline{UB} and \overline{LB} .

5. The address counter advances if CNTEN = VIL on the rising edge of CLK, regardless of all other signals including CEo, CE1, UB and LB.

6. While an external address is being loaded ($\overline{ADS} = V_{IL}$), $R/\overline{W} = V_{IH}$ is recommended to ensure data is not written arbitrarily.

Recommended Operating Temperature and Supply Voltage

Grade	Grade Ambient Temperature ⁽²⁾		Vcc
Commercial	0°C to +70°C	0V	5.0V <u>+</u> 10%
Industrial	-40°C to +85°C	0V	5.0V <u>+</u> 10%

NOTES:

1. This is the parameter TA. This is the "instant on" case temperature.

Absolute Maximum Ratings⁽¹⁾

Recommended DC Operating Conditions

Symbol	Parameter	Min.	Тур.	Мах.	Unit
Vcc	Supply Voltage	4.5	5.0	5.5	V
GND	Ground	0	0	0	V
VIH	Input High Voltage	2.2		6.0 ⁽¹⁾	V
VIL	Input Low Voltage	-0.5 ⁽²⁾		0.8	V

NOTES:

4845 tbl 04

4845 tbl 06

1. VTERM must not exceed Vcc + 10%.

2. VIL \geq -1.5V for pulse width less than 10ns.

Symbol	Rating	Commercial & Industrial	Unit
Vterm ⁽²⁾	Terminal Voltage with Respect to GND	-0.5 to +7.0	V
Tbias	Temperature Under Bias	-55 to +125	٥C
Tstg	Storage Temperature	-65 to +150	٥C
Тли	Junction Temperature	+150	٥C
Ιουτ	DC Output Current	50	mA

NOTES:

 Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

2. VTERM must not exceed Vcc + 10% for more than 25% of the cycle time or 10ns maximum, and is limited to \leq 20mA for the period of VTERM \geq Vcc + 10%.

3. Ambient Temperature Under Bias. No AC Conditions. Chip Deselected.

Capacitance⁽¹⁾ (TA = $+25^{\circ}$ C, f = 1.0MHz)

Symbol	Parameter	Conditions ⁽²⁾	Мах.	Unit
Cin	Input Capacitance	VIN = 3dV	9	pF
Cout ⁽³⁾	Output Capacitance	Vout = 3dV	10	pF
				4845 tbl 07

NOTES:

1. These parameters are determined by device characterization, but are not production tested.

2. 3dV references the interpolated capacitance when the input and output switch from 0V to 3V or from 3V to 0V.

3. COUT also references CI/O.

Industrial and Commercial Temperature Ranges

4845 tbl 08

DC Electrical Characteristics Over the Operating <u>Temperature Supply Voltage Range ($Vcc = 5.0V \pm 10\%$)</u>

			70937	9/69L	
Symbol	Parameter	Test Conditions	Min.	Max.	Unit
lu	Input Leakage Current ⁽¹⁾	Vcc = 5.5V, VIN = 0V to Vcc	—	5	μA
Ilo	Output Leakage Current	$\overline{CE}_0 = V_{IH} \text{ or } CE_1 = V_{IL}, V_{OUT} = 0V \text{ to } V_{CC}$	_	5	μA
Vol	Output Low Voltage	Iol = +4mA	—	0.4	V
Vон	Output High Voltage	Юн = -4mA	2.4	_	V

NOTE:

1. At Vcc \leq 2.0V input leakages are undefined.

DC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range^{(3)} (Vcc = 5V \pm 10%)

				709379/69L7 Com'l Only		Co		709379/69L12 Com'l Only		
Parameter	Test Condition	Versie	on	Тур. ⁽⁴⁾	Max.	Тур. ⁽⁴⁾	Мах.	Тур. ⁽⁴⁾	Max.	Unit
CC Dynamic Operating CEL and CER= VIL		COM'L	L	250	440	250	400	230	355	mA
(Both Ports Active)	$f = fMAX^{(1)}$	IND	L			300	430			
Standby Current	$\overline{CEL} = \overline{CER} = VIH$	COM'L	L	65	145	80	135	70	110	mA
(Both Ports - TTL Level Inputs)	$T = TMAX^{(1)}$	IND	L			95	160			
Standby Current	e Port - TTL $\overline{CE}"B" = VH^{(3)}$	COM'L	L	160	295	175	275	150	240	mA
(One Port - TTL Level Inputs)		IND	L			175	295		_	
Full Standby Current	Both Ports CER and	COM'L	L	0.2	5.0	0.5	3.0	0.5	3.0	mA
(Both Ports - CMOS Level Inputs)	$\begin{array}{l} \text{CEL} \geq \text{VCC} - 0.2\text{V} \\ \text{VIN} \geq \text{VCC} - 0.2\text{V} \text{ or} \\ \text{VIN} \leq 0.2\text{V}, \text{ f} = 0^{(2)} \end{array}$	IND	L			0.5	6.0			
Full Standby Current	\overline{CE} "A" < 0.2V and	COM'L	L	150	290	170	270	140	225	mA
CMOS Level Inputs)	CMOS Level Inputs) $VIN \ge VCC - 0.2V$ or VIN < 0.2V, Active Port	IND	L		_	190	290	—		
	Dynamic Operating Current (Both Ports Active) Standby Current (Both Ports - TTL Level Inputs) Standby Current (One Port - TTL Level Inputs) Full Standby Current (Both Ports - CMOS Level Inputs) Full Standby Current (One Port -	Dynamic Operating Current (Both Ports Active) \overline{CE}_{L} and $\overline{CE}_{R} = VIL$ Outputs Disabled $f = fMAX^{(1)}$ Standby Current (Both Ports - TTL Level Inputs) $\overline{CE}_{L} = \overline{CE}_{R} = VIH$ $f = fMAX^{(1)}$ Standby Current (One Port - TTL Level Inputs) $\overline{CE}_{R}^{*} = VIL$ and $\overline{CE}_{R}^{*} = VIL$ and $\overline{CE}_{R}^{*} = VIL$ Active Port Outputs Disabled, $f = fMAX^{(1)}$ Full Standby Current (Both Ports - CMOS Level Inputs)Both Ports CER and $\overline{CE}_{L} \ge Vcc - 0.2V$ $VIN \ge Vcc - 0.2V$ or $VIN \le 0.2V$, $f = 0^{(2)}$ Full Standby Current (One Port - CMOS Level Inputs) $\overline{CE}_{R}^{*}^{*} \le 0.2V$ and $\overline{CE}_{R}^{*}^{*} \ge Vcc - 0.2V'$ or $VIN \ge Vcc - 0.2V (r)$ $VIN \ge Vcc - 0.2V (r)$	$ \begin{array}{c c} \hline \text{Dynamic Operating} \\ \text{Current} \\ (\text{Both Ports Active}) & \hline \overline{\text{CE}} \text{L and } \overline{\text{CE}} \text{R} = \text{VIL} \\ \text{Outputs Disabled} \\ f = fMAX^{(1)} & \hline \text{IND} \\ \hline \text{IND} \\ \hline \text{Standby Current} \\ (\text{Both Ports - TTL} \\ \text{Level Inputs}) & \hline \overline{\text{CE}} \text{L} = \overline{\text{CE}} \text{R} = \text{VIH} \\ f = fMAX^{(1)} & \hline \text{IND} \\ \hline \hline \text{IND} \\ \hline \text{Standby Current} \\ (\text{One Port - TTL} \\ \text{Level Inputs}) & \hline \overline{\text{CE}}^{\text{E}} \text{A}^{\text{e}} = \text{VIL and} \\ \hline \overline{\text{CF}} \text{B}^{\text{e}} = \text{VIH}^{(3)} \\ \text{Active Port Outputs} \\ \hline \text{Disabled, } f = fMAX^{(1)} \\ \hline \text{IND} \\ \hline \hline \\ \hline \text{Full Standby Current} \\ (\text{Both Ports -} \\ \text{CMOS Level Inputs}) & \hline \hline \overline{\text{CE}}^{\text{E}} \text{A}^{\text{e}} \leq 0.2 \text{V and} \\ \hline \hline \\ \hline $	$ \begin{array}{c c} \mbox{Dynamic Operating} \\ \mbox{Current} \\ \mbox{(Both Ports Active)} \end{array} & \hline \hline C\overline{E}L and \overline{C}\overline{E}R = VIL \\ \mbox{Outputs Disabled} \\ \mbox{f} = fMAX^{(1)} \end{array} & \hline \hline IND \\ \hline IND \\ \mbox{L} \end{array} \\ \hline \mbox{Standby Current} \\ \mbox{(Both Ports - TTL Level Inputs)} \end{array} & \hline \hline C\overline{E}L = \overline{C}\overline{E}R = VIH \\ \mbox{f} = fMAX^{(1)} \end{array} & \hline \hline COM'L \\ \hline \mbox{L} \\ \hline \mbox{IND} \\ \mbox{L} \end{array} \\ \hline \mbox{Standby Current} \\ \mbox{(One Port - TTL Level Inputs)} \end{array} & \hline \hline C\overline{E}^{*}A^{*} = VIL and \\ \hline \hline C\overline{E}^{*}B^{*} = VIH^{(3)} \\ \mbox{Active Port Outputs} \\ \mbox{Disabled, } f = fMAX^{(1)} \end{array} & \hline \hline \mbox{IND} \\ \hline \mbox{L} \\ \hline \mbox{IND} \\ \hline \mbox{L} \end{array} \\ \hline \mbox{Full Standby Current} \\ \mbox{(Both Ports - Comos Level Inputs)} \end{array} & \hline \mbox{Both Ports CER and} \\ \hline \mbox{CEL } VCc - 0.2V \\ \mbox{VIN } \leq 0.2V, f = 0^{(2)} \end{array} & \hline \mbox{IND} \\ \hline \mbox{IND} \\ \hline \mbox{L} \\ \hline \mbox{IND} \\ \hline \mbox{L} \\ \hline \mbox{Full Standby Current} \\ \mbox{(One Port - Comos Level Inputs)} \end{array} & \hline \hline \mbox{CE}^{*}A^{*} \leq 0.2V and \\ \hline \mbox{CE}^{*}B^{*} \geq Vcc - 0.2V^{(5)} \\ \mbox{VIN } \leq 0.2V, f = 0^{(2)} \end{array} & \hline \mbox{IND} \\ \hline \mbox{L} \\ \hline \mbox{IND} \\ \hline \ \mbox{L} \\ \hline \mbox{IND} \\ \hline \mbox{L} \\ \hline \mbox{IND} \\ \hline \mbox{L} \\ \hline \mbox{IND} \\ \hline \mbox{IND} \\ \hline \mbox{IND} \\ \hline \ \mbox{IND} \\ \hline \mbox{IND} \\ \hline \mbox{IND} \\ \hline \ \ \mbox{IND} \\ \hline \ \mbox{IND} \\ \hline \ \mbox{IND} \\ \hline \ \mbox{IND} \\ \hline \ \ \ \mbox{IND} \\ \hline \ \ \ \mbox{IND} \\ \hline \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \$	ParameterTest ConditionVersionTyp. (4)Dynamic Operating Current (Both Ports Active) \overline{CEL} and $\overline{CER} = VIL$ Outputs Disabled f = fMAX ⁽¹⁾ $COM'L$ L250Standby Current (Both Ports - TTL Level Inputs) $\overline{CEL} = \overline{CER} = VIH$ f = fMAX ⁽¹⁾ $COM'L$ L65Standby Current (Both Ports - TTL Level Inputs) $\overline{CE}^{*}A^{*} = VIH$ and $\overline{CE}^{*}A^{*} = VIL$ and $\overline{CE}^{*}B^{*} = VIH^{(3)}$ Active Port Outputs Disabled, f=fMAX ⁽¹⁾ $COM'L$ L160Standby Current (One Port - TTL Level Inputs) $\overline{CE}^{*}A^{*} = VIL$ and $\overline{CE}^{*}A^{*} = VIL(3)$ Active Port Outputs Disabled, f=fMAX ⁽¹⁾ $COM'L$ L160Full Standby Current (One Port - CMOS Level Inputs) $\overline{CE}^{*}A^{*} = 0.2V$ and $\overline{CE}^{*}B^{*} = Vic - 0.2V'$ or $VIN \ge Vcc - 0.2V$ or $VIN \ge Vcc - 0.2V'$ or $VIN \ge Vcc - 0$	ParameterTest ConditionVersionTyp. (*)Max.Dynamic Operating Current (Both Ports Active) $\overline{CE}L$ and $\overline{CE}R = VIL$ Outputs Disabled f = fMAX ⁽¹⁾ $COM'L$ L250440INDLStandby Current (Both Ports - TTL Level Inputs) $\overline{CE}L = \overline{CE}R = VIH$ f = fMAX ⁽¹⁾ $COM'L$ L65145Standby Current (One Port - TTL Level Inputs) $\overline{CE}^{-}A^* = VIL$ and $\overline{CE}^{-}A^* = VIL and$ $\overline{CE}^{-}B^* = VIH^{(3)}$ Active Port Outputs Disabled, f=fMAX ⁽¹⁾ $COM'L$ L160295Full Standby Current (One Port - CMOS Level Inputs)Both Ports CER and $\overline{CE}L \ge Vcc - 0.2V$ or $VIN \ge 0.2V$, f = 0 ⁽²⁾ $COM'L$ L0.25.0Full Standby Current (One Port - CMOS Level Inputs) $\overline{CE}^{-}A^* \le 0.2V$ and $\overline{CE}^{-}B^* \ge Vcc - 0.2V^{(5)}$ $VIN \ge Vcc - 0.2V$ or $VIN \ge Vcc - 0.2V$ or V	ParameterTest ConditionVersionTyp.(4)Max.Typ.(4)Dynamic Operating Current (Both Ports Active) \overline{CE} and $\overline{CE}_{R} = VILOutputs Disabledf = fMAX(1)COM'LL250440250INDL300Standby Current(Both Ports - TTLLevel Inputs)\overline{CE} L = \overline{CE}_R = VIHf = fMAX(1)COM'LL6514580Standby Current(One Port - TTLLevel Inputs)\overline{CE} A'' = VIL and\overline{CE} B'' = VIH^{(3)}Active Port OutputsDisabled, f=fMAX(1)COM'LL160295175Standby Current(One Port - TTLLevel Inputs)\overline{CE} A'' = VIH^{(3)}Active Port OutputsDisabled, f=fMAX(1)COM'LL160295175Full Standby Current(Both Ports -CMOS Level Inputs)Both Ports CER and\overline{CE} A'' = 0.2V orVIN \geq 0.2V, f = 0^{(2)}COM'LL0.25.00.5Full Standby Current(One Port -CMOS Level Inputs)\overline{CE} A'' = 0.2V and\overline{CE} B'' = VIC - 0.2V' orVIN \geq 0.2V, f = 0^{(2)}COM'LL150290170Full Standby Current(One Port -CMOS Level Inputs)\overline{CE} A'' = 0.2V' and\overline{CE} B'' = VIC - 0.2V' orVIN \geq 0.2V, Active PortCOM'LL150290170Full Standby Current(One Port -CMOS Level Inputs)\overline{CE} A'' = 0.2V' orVIN \geq VCC - 0.2V' orVIN \geq VCC -$	Parameter Test Condition Version Typ. ⁽⁴⁾ Max. Typ. ⁽⁴⁾ Max. Dynamic Operating Current (Both Ports Active) \overline{CE}_{L} and $\overline{CE}_{R} = V_{IL}$ (Both Ports Active) \overline{CE}_{L} and $\overline{CE}_{R} = V_{IL}$ f = fMAX ⁽¹⁾ $COM'L$ L 250 440 250 400 Standby Current (Both Ports - TTL Level Inputs) $\overline{CE}_{L} = \overline{CE}_{R} = V_{IH}$ f = fMAX ⁽¹⁾ $\overline{COM'L}$ L 65 145 80 135 Standby Current (Done Port - TTL Level Inputs) $\overline{CE}_{R}^{*} = V_{IL}$ and $\overline{CE}_{B}^{*} = V_{H}^{(3)}$ Active Port Outputs Disabled, f=fMAX ⁽¹⁾ $\overline{COM'L}$ L 160 295 175 275 Full Standby Current (Both Ports - CMOS Level Inputs) Both Ports CER and $\overline{CE}_{L} \ge VCC - 0.2V$ or $V_{IN} \le 0.2V$, $f = 0^{(2)}$ $\overline{COM'L}$ L 0.2 5.0 0.5 3.0 Full Standby Current (One Port - CMOS Level Inputs) $\overline{CE}_{A}^{*} < 0.2V$ and $\overline{CE}_{B}^{*} \ge VCC - 0.2V^{(5)}$ $V_{IN} \le 0.2V, Active Port \overline{COM'L} L 150 2.90 170 270 Full Standby Current(One Port -CMOS Level Inputs) \overline{CE}_{A}^{*} < 0.2V and\overline{CE}_{B}^{*} \ge VCC - 0.2V^{(5)}V_{IN} < 0.2V, Active Port$	Parameter Test Condition Version Typ. ⁽⁴⁾ Max. Typ. ⁽⁴⁾	Parameter Test Condition Version Typ. ⁽⁴⁾ Max. Typ. ⁽⁴⁾

NOTES:

1. At f = fMax, address and control lines (except Output Enable) are cycling at the maximum frequency clock cycle of 1/tcyc, using "AC TEST CONDITIONS" at input levels of GND to 3V.

2. f = 0 means no address, clock, or control lines change. Applies only to input at CMOS level standby.

3. Port "A" may be either left or right port. Port "B" is the opposite from port "A".

4. Vcc = 5V, TA = 25°C for Typ, and are not production tested. Icc cc(f=0) = 150mA (Typ).

- 5. $CEx = VIL \text{ means } \overline{CE}ox = VIL \text{ and } CE1x = VIH$
 - $CEx = VIH means \overline{CE}_{0X} = VIH or CE_{1X} = VIL$
 - $CEx \leq 0.2V$ means $\overline{CE}\textsc{ox} \leq 0.2V$ and $CE1x \geq Vcc$ 0.2V

 $CEx \ge Vcc$ - 0.2V means $\overline{CE} \text{ox} \ge Vcc$ - 0.2V or $CE1x \le 0.2V$

"X" represents "L" for left port or "R" for right port.

709379/69L High-Speed 32/16K x 18 Synchronous Pipelined Dual-Port Static RAM

Industrial and Commercial Temperature Ranges

5У

893Ω

5pF*

4845 drw 05

AC Test Conditions

Input Pulse Levels	GND to 3.0V				
Input Rise/Fall Times	3ns Max.				
Input Timing Reference Levels 1.5V					
Output Reference Levels	1.5V				
Output Load	Figures 1,2 and 3				



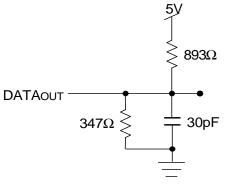




Figure 1. AC Output Test load.

Figure 2. Output Test Load (For tcкLz, tcкнz, toLz, and toнz). *Including scope and jig.

 $347\Omega \leq$

DATAOUT

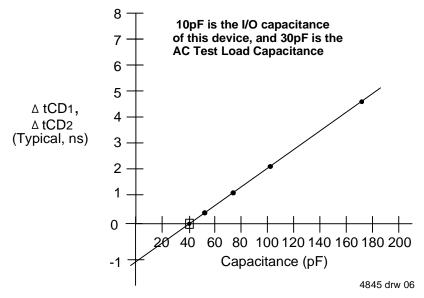


Figure 3. Typical Output Derating (Lumped Capacitive Load).

AC Electrical Characteristics Over the Operating Temperature Range (Read and Write Cycle Timing)⁽³⁾ ($Vcc = 5V \pm 10\%$)

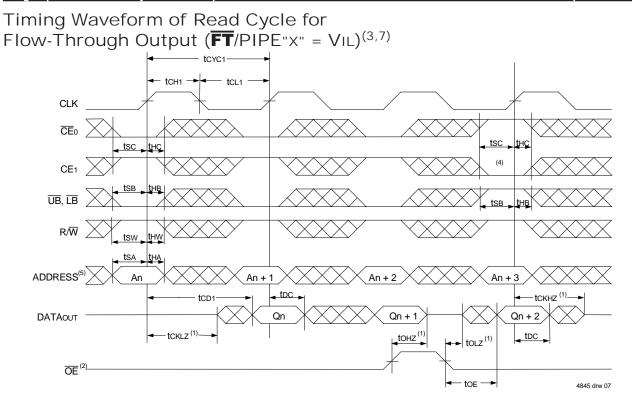
			9/69L7 I Only	Co	9/69L9 m'l Ind	709379 Com		
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Unit
tcyc1	Clock Cycle Time (Flow-Through) ⁽²⁾	22		25		30	—	ns
tcyc2	Clock Cycle Time (Pipelined) ⁽²⁾	12	—	15	_	20	—	ns
tCH1	Clock High Time (Flow-Through) ⁽²⁾	7.5		12	_	12		ns
tcl1	Clock Low Time (Flow-Through) ⁽²⁾	7.5		12	_	12		ns
tch2	Clock High Time (Pipelined) ⁽²⁾	5		6	_	8		ns
tCL2	Clock Low Time (Pipelined) ⁽²⁾	5	—	6	_	8	—	ns
tR	Clock Rise Time		3		3	_	3	ns
tF	Clock Fall Time		3		3	—	3	ns
tsa	Address Setup Time	4	_	4	_	4	_	ns
tha	Address Hold Time	0	—	1	_	1	_	ns
tsc	Chip Enable Setup Time	4	—	4	_	4	—	ns
tнc	Chip Enable Hold Time	0		1		1		ns
tsв	Byte Enable Setup Time	4	—	4	_	4	—	ns
tнв	Byte Enable Hold Time	0	—	1	_	1	_	ns
tsw	R/W Setup Time	4	—	4	_	4	—	ns
tнw	R/W Hold Time	0		1		1		ns
tsd	Input Data Setup Time	4	—	4	_	4	—	ns
thd	Input Data Hold Time	0		1		1		ns
tsad	ADS Setup Time	4		4	_	4	_	ns
thad	ADS Hold Time	0		1		1		ns
tscn	CNTEN Setup Time	4		4		4	_	ns
then	CNTEN Hold Time	0		1		1		ns
t SRST	CNTRST Setup Time	4		4		4		ns
thrst	CNTRST Hold Time	0		1	_	1		ns
toe	Output Enable to Data Valid		7.5		9	_	12	ns
tolz	Output Enable to Output Low-Z ⁽¹⁾	2		2		2		ns
toнz	Output Enable to Output High-Z ⁽¹⁾	1	7	1	7	1	7	ns
tCD1	Clock to Data Valid (Flow-Through) ⁽²⁾		18		20	_	25	ns
tCD2	Clock to Data Valid (Pipelined) ⁽²⁾		7.5		9	_	12	ns
tDC	Data Output Hold After Clock High	2		2		2		ns
tскнz	Clock High to Output High-Z ⁽¹⁾	2	9	2	9	2	9	ns
tскız	Clock High to Output Low-Z ⁽¹⁾	2		2		2		ns
Port-to-Port I	Delay		•		•	•	•	
tcwdd	Write Port Clock High to Read Data Delay		28		35	_	40	ns
tccs	Clock-to-Clock Setup Time		10		15	1	15	ns

1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2). This parameter is guaranteed by device characterization, but is not production tested.

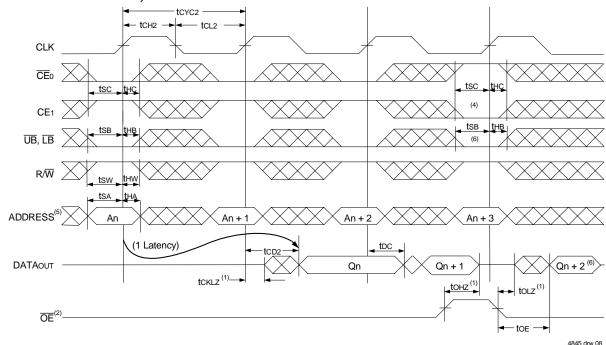
2. The Pipelined output parameters (tcyc2, tcp2) to either the Left or Right ports when FT/PIPE = VIH. Flow-Through parameters (tcyc1, tcp1) apply when FT/PIPE = VIL for that port.

3. All input signals are synchronous with respect to the clock except for the asynchronous Output Enable (OE), FT/PIPER and FT/PIPEL.

High-Speed 32/16K x 18 Synchronous Pipelined Dual-Port Static RAM

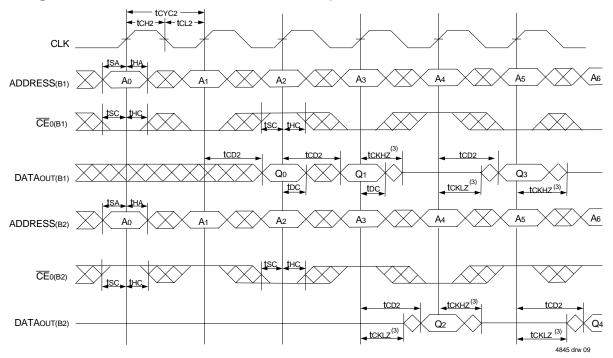


Timing Waveform of Read Cycle for Pipelined Operation $(FT/PIPE"x" = VIH)^{(3,7)}$

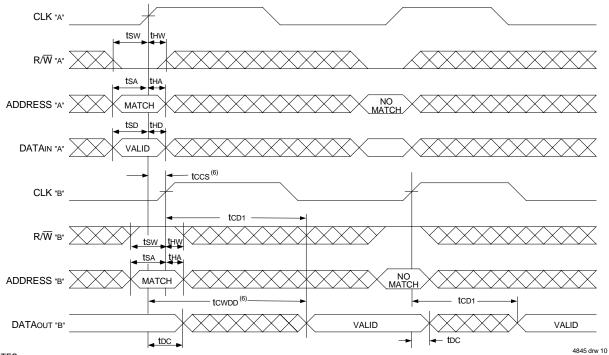


- 1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 2. OE is asynchronously controlled; all other inputs are synchronous to the rising clock edge.
- 3. $\overline{ADS} = V_{IL}$ and $\overline{CNTRST} = V_{IH}$.
- 4. The output is disabled (High-Impedance state) by $\overline{CE}_0 = V_{IH}$, $CE_1 = V_{IL}$, $\overline{UB} = V_{IH}$, or $\overline{LB} = V_{IH}$ following the next rising edge of the clock. Refer to Truth Table 1. 5. Addresses do not have to be accessed sequentially since $\overline{ADS} = V_{IL}$ constantly loads the address on the rising edge of the CLK; numbers
- are for reference use only.
 If UB or LB was HIGH, then the Upper Byte and/or Lower Byte of DATAout for Qn + 2 would be disabled (High-Impedance state).
- 7. "X" here denotes Left or Right port. The diagram is with respect to that port.

Timing Waveform of a Bank Select Pipelined Read^(1,2)

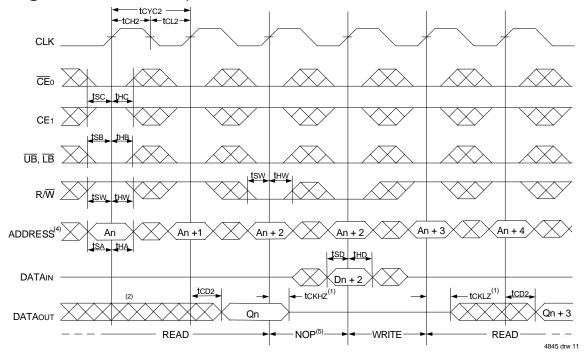


Timing Waveform of Write with Port-to-Port Flow-Through Read^(4,5,7)

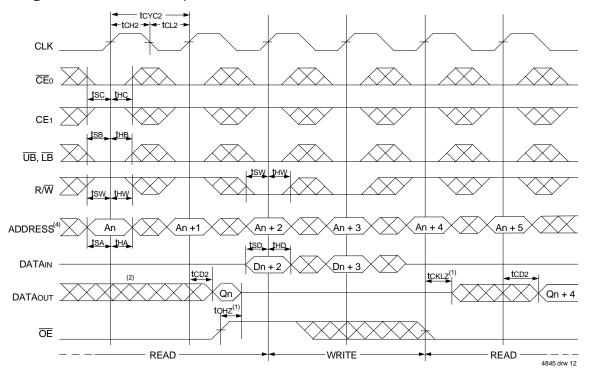


- 1. B1 Represents Bank #1; B2 Represents Bank #2. Each Bank consists of one IDT709379/69 for this waveform, and are setup for depth expansion in this example. ADDRESS(B1) = ADDRESS(B2) in this situation.
- 2. \overline{UB} , \overline{LB} , \overline{OE} , and \overline{ADS} = VIL; CE1(B1), CE1(B2), R/W and \overline{CNTRST} = VIH.
- 3. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 4. \overline{CE}_{0} , \overline{UB} , \overline{LB} , and $\overline{ADS} = VIL$; CE1 and $\overline{CNTRST} = VIH$.
- 5. $\overline{OE} = V_{IL}$ for the Right Port, which is being read from. $\overline{OE} = V_{IH}$ for the Left Port, which is being written to.
- If tccs ≤ maximum specified, then data from right port READ is not valid until the maximum specified for tcwbb. If tccs > maximum specified, then data from right port READ is not valid until tccs + tcb1. tcwbb does not apply in this case.
- 7. All timing is the same for both Left and Right ports. Port "A" may be either Left or Right port. Port "B" is the opposite from Port "A".

Timing Waveform of Pipelined Read-to-Write-to-Read ($\overline{OE} = VIL$)⁽³⁾

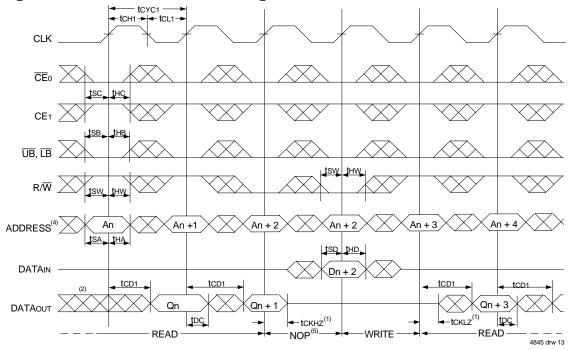


Timing Waveforn of Pipelined Read-to-Write-to-Read (**OE** Controlled)⁽³⁾

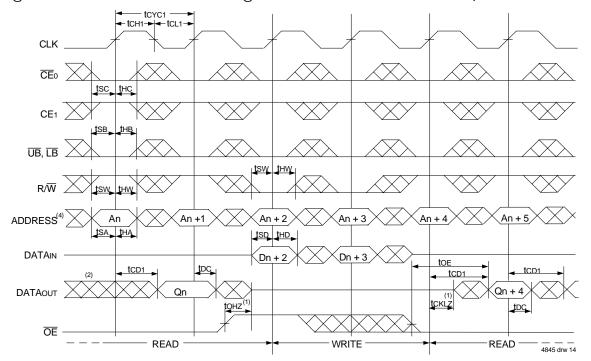


- 1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 2. Output state (High, Low, or High-impedance) is determined by the previous cycle control signals.
- 3. CEo, UB, LB, and ADS = VIL; CE1 and CNTRST = VIH. "NOP" is "No Operation".
- 4. Addresses do not have to be accessed sequentially since ADS = VIL constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- 5. "NOP" is "No Operation." Data in memory at the selected address may be corrupted and should be re-written to guarantee data integrity.

Timing Waveform of Flow-Through Read-to-Write-to-Read ($\overline{OE} = VIL$)⁽³⁾

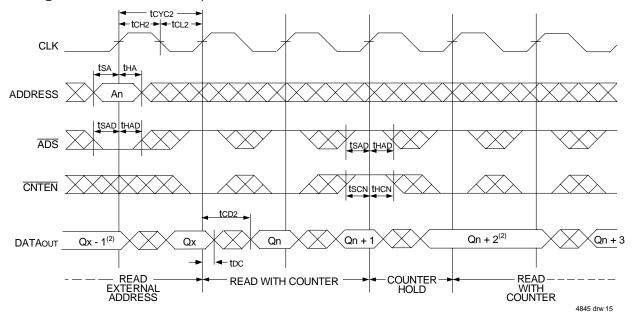


Timing Waveform of Flow-Through Read-to-Write-to-Read (**OE** Controlled)⁽³⁾

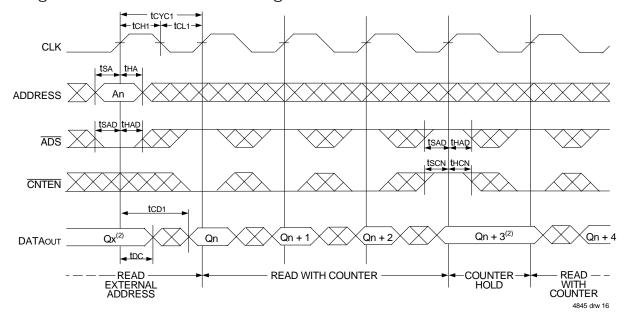


- 1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 2. Output state (High, Low, or High-impedance is determined by the previous cycle control signals.
- 3. \overline{CE}_0 , \overline{UB} , \overline{LB} , and $\overline{ADS} = V_{IL}$; CE1 and $\overline{CNTRST} = V_{IH}$. "NOP" is "No Operation".
- 4. Addresses do not have to be accessed sequentially since ADS = VIL constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- 5. "NOP" is "No Operation." Data in memory at the selected address may be corrupted and should be re-written to guarantee data integrity.

Timing Waveform of Pipelined Read with Address Counter Advance⁽¹⁾

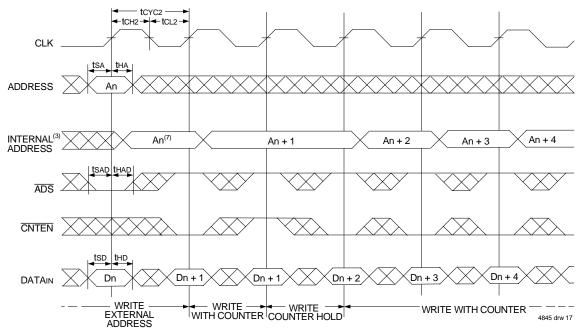


Timing Waveform of Flow-Through Read with Address Counter Advance⁽¹⁾

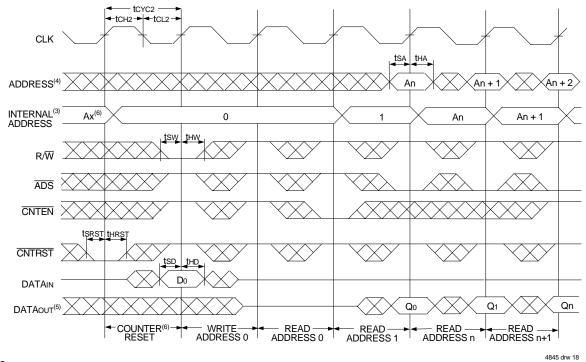


- 1. \overline{CE}_{0} , \overline{OE} , \overline{UB} , and $\overline{LB} = VIL$; CE1, R/W, and $\overline{CNTRST} = VIH$.
- 2. If there is no address change via $\overline{ADS} = VIL$ (loading a new address) or $\overline{CNTEN} = VIL$ (advancing the address), i.e. $\overline{ADS} = VIH$ and $\overline{CNTEN} = VIH$, then the data output remains constant for subsequent clocks.

Timing Waveform of Write with Address Counter Advance (Flow-Through or Pipelined Outputs)⁽¹⁾



Timing Waveform of Counter Reset (Pipelined Outputs)⁽²⁾



NOTES: 1. \overline{CE}_0 , \overline{UB} , \overline{LB} , and $R/\overline{W} = V_{IL}$; CE_1 and $\overline{CNTRST} = V_{IH}$.

- 3. The "Internal Address" is equal to the "External Address" when ADS = VIL and equals the counter output when ADS = VIH.
- 4. Addresses do not have to be accessed sequentially since $\overline{ADS} = VIL$ constantly loads the address on the rising edge of the CLK; numbers are for reference use only. 5. Output state (High, Low, or High-impedance) is determined by the previous cycle control signals.
- No dead cycle exists during counter reset. A READ or WRITE cycle may be coincidental with the counter reset cycle. 6.
- CNTEN = VIL advances Internal Address from 'An' to 'An +1'. The transition shown indicates the time required for the counter to advance. The 'An +1' Address is written 7. to during this cycle.

 $[\]overline{CE}_{0}, \overline{UB}, \overline{LB} = VIL; CE1 = VIH.$ 2

709379/69L

High-Speed 32/16K x 18 Synchronous Pipelined Dual-Port Static RAM

Industrial and Commercial Temperature Ranges

A Functional Description

The IDT709379/69 provides a true synchronous Dual-Port Static RAM interface. Registered inputs provide minimal set-up and hold times on address, data, and all critical control inputs. All internal registers are clocked on the rising edge of the clock signal, however, the self-timed internal write pulse is independent of the LOW to HIGH transition of the clock signal.

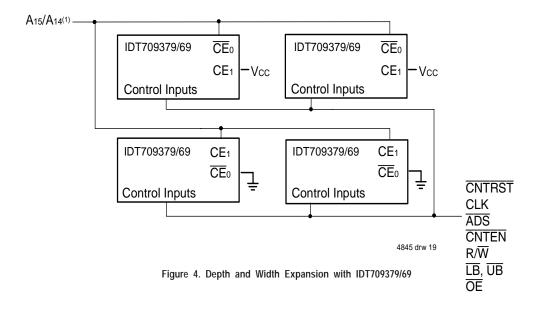
An asynchronous output enable is provided to ease asynchronous bus interfacing. Counter enable inputs are also provided to stall the operation of the address counters for fast interleaved memory applications.

 $\overline{CE}_0 = V_{IH}$ or CE1 = VIL for one clock cycle will power down the internal circuitry to reduce static power consumption. Multiple chip enables allow easier banking of multiple IDT709379/69's for depth expansion configurations. When the Pipelined output mode is enabled, two cycles are required with $\overline{CE}_0 = V_{IL}$ and CE1 = VIH to reactivate the outputs.

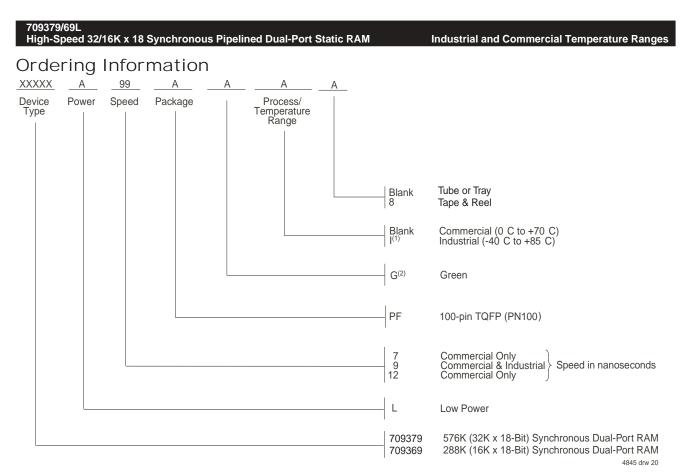
Depth and Width Expansion

The IDT709379/69 features dual chip enables (refer to Truth Table I) in order to facilitate rapid and simple depth expansion with no requirements for external logic. Figure 4 illustrates how to control the various chip enables in order to expand two devices in depth.

The IDT709379/69 can also be used in applications requiring expanded width, as indicated in Figure 4. Since the banks are allocated at the discretion of the user, the external controller can be set up to drive the input signals for the various devices as required to allow for 36-bit or wider applications.



NOTE: 1. A14 is for IDT709369.



NOTES:

1. Industrial temperature range is available. For other speeds, packages and powers contact your sales office

Green parts available. For specific speeds, packages and powers contact your sales office. 2. LEAD FINISH (SnPb) parts are in EOL process. Product Discontinuation Notice - PDN# SP-17-02

Note that information regarding recently obsoleted parts is included in this datasheet for customer convenience.

Industrial and Commercial Temperature Ranges

Datasheet Document History

9/30/99:		Initial Public Release
11/10/99:		Replaced IDT log
12/22/99:	Page 1	Added nmissing diamond
1/12/01:	Page 4	Changed information in Truth Table II
	5	Increased storage temperature parameter
		Clarified TA parameter
	Page 5	DC Electrical parameters-changed wording from "open" to "disabled"
	5	Changed ±200mV to 0mV in notes
		Removed Preliminary status
04/26/04:		Consolidated multiple devices into one datasheet
		Removed I-temp footnote
	Page 2	Added date revision to pin configuration
	Page 4	Added Junction Temperature to Absolute Maximum Ratings Table
	0	Added Ambient Temperature footnote
	Page 5	Added I-temp numbers for 9ns speed to the DC Electrical Characteristics Table
	0	Added 6ns speed DC timing numbers to the DC Electrical Characteristics Table
	Page 7	Added I-temp for 9ns speed to AC Electrical Characteristics Table
	Ū	Added 6ns speed AC timing numbers to the AC Electrical Characteristics Table
	Page 15	Added 6ns speed grade and 9ns I-temp to ordering information
	-	Added IDT Clock Solution Table
	Page 1 & 16	Replaced old тм logo with new тм logo
01/29/09:	Page 15	Removed "IDT" from orderable part number
07/26/10:	Page 1	Added green parts availability to features
	Page 15	Added green indicator to ordering information
	Page 7	In order to correct the header notes of the AC Elect Chars Table and align them with the Industrial temp range
		values located in the table, the commercial TA header note has been removed
	Pages 8-11	In order to correct the footnotes of timing diagrams, CNTEN has been removed to reconcile the footnotes with the CNTEN logic definition found in Truth Table II - Address Counter Control
07/16/15:	Page 1	Updated speed offerings by removing the 6.5ns commercial grade in Features
	Page 2	Removed IDT in reference to fabrication
	Page 2 & 15	The package code PN100-1 changed to PN100 to match standard package codes
	Page 5	Removed X6 speed grade from the DC Elec Chars table
	Page 6	Corrected typo in the Typical Output Derating drawing
	Page 7	Removed X6 speed grade from the AC Elec Chars table
	Page 16	Added Tape and Reel indicator to, removed X6 speed grade and updated the commercial offerings in
	r ugo ro	Ordering Information
	Page 15	Removed the IDT Clock Solution table
02/08/18:	5	Product Discontinuation Notice - PDN# SP-17-02
		Last time buy expires June 15, 2018
04/24/19:		709369 is obsolete
		709379 is still active



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